

# LH5168

## CMOS 64K (8K × 8) Static Ram

### FEATURES

- 8,192 × 8 bit organization
- Access times: 80/100 ns (MAX.)
- Low-power consumption:
  - Operating:
    - 303 mW (MAX.) LH5168/D/N
      - @ 80 ns
    - 248 mW (MAX.) LH5168/D/N/T/TR
      - @ 100 ns
    - 275 mW (MAX.) LH5168H/HD/HN
      - @ 100 ns
  - Standby:
    - 5.5 μW (MAX.) LH5168/D/N/T/TR
    - 16.5 μW (MAX.) LH5168H/HD/HN
- Fully-static operation
- Three-state outputs
- Single +5 V power supply
- TTL compatible I/O
- Pin compatible to 64K bit EPROM
- Wide temp. range available
  - LH5168: -10 to +70°C
  - LH5168H: -40 to +85°C
- Packages:
  - 28-pin, 600-mil DIP
  - 28-pin, 300-mil SK-DIP
  - 28-pin, 450-mil SOP
  - 28-pin, 8 × 13 mm<sup>2</sup> TSOP (Type I)

### DESCRIPTION

The LH5168 is a static RAM organized as 8,192 × 8 bits. It is fabricated using silicon-gate CMOS process technology.

The LH5168H is designed for wide temperature range from -40 to +85°C.

### PIN CONNECTIONS

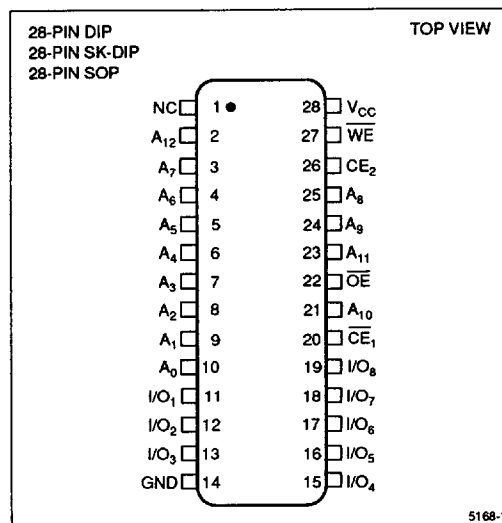


Figure 1. Pin Connections for DIP, SK-DIP, and SOP Packages

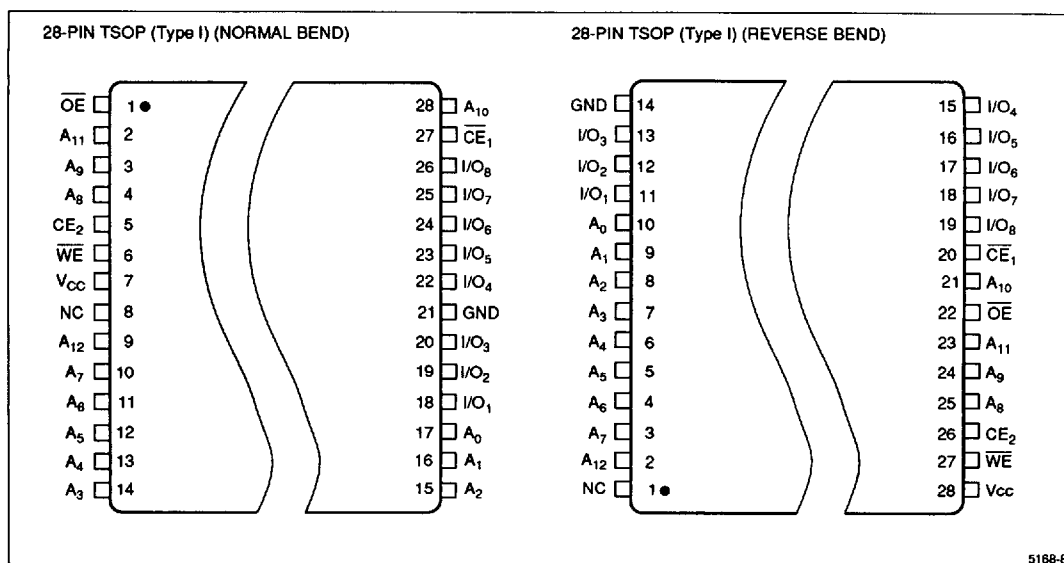


Figure 2. Pin Connections for TSOP Packages

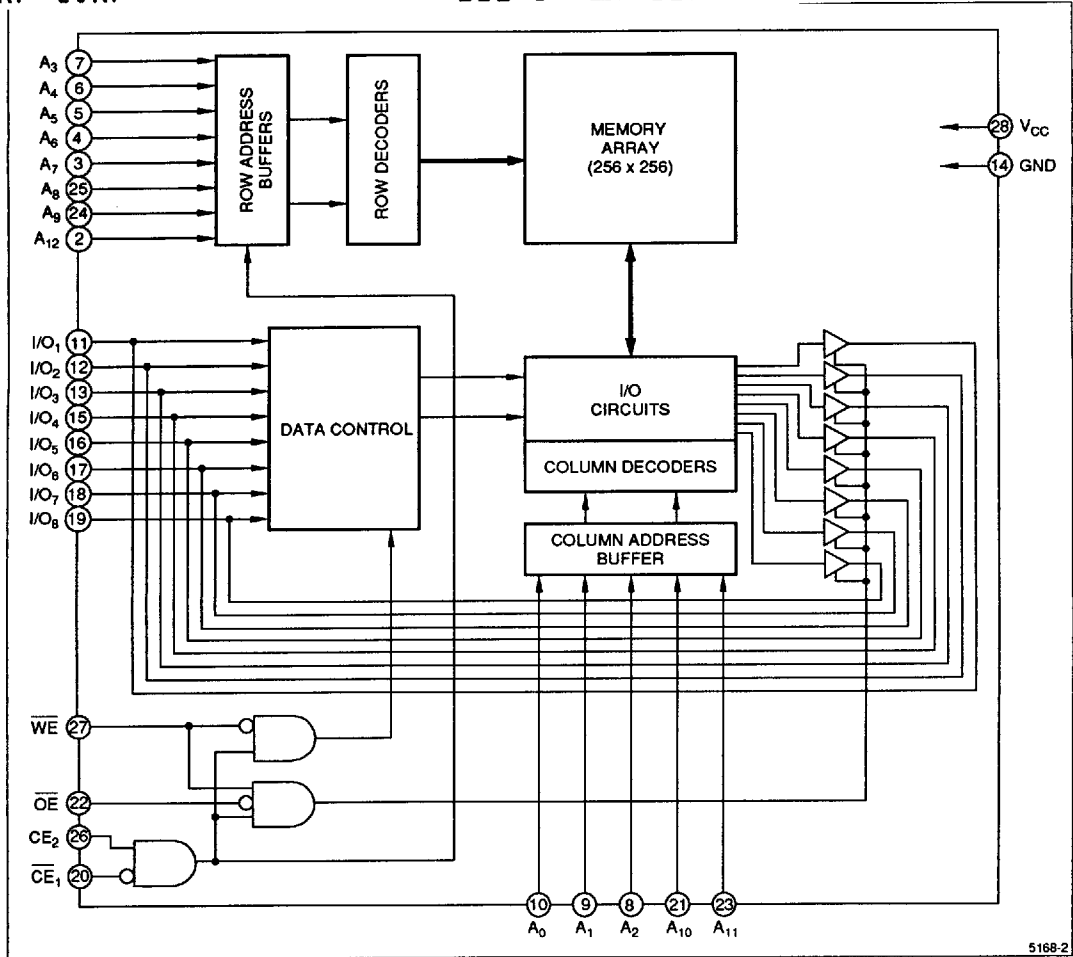


Figure 3. LH5168 Block Diagram

**PIN DESCRIPTION**

| SIGNAL                                | PIN NAME            |
|---------------------------------------|---------------------|
| A <sub>0</sub> - A <sub>12</sub>      | Address inputs      |
| $\overline{CE}_1$ - $\overline{CE}_2$ | Chip Enable input   |
| $\overline{WE}$                       | Write Enable input  |
| $\overline{OE}$                       | Output Enable input |

| SIGNAL                              | PIN NAME                |
|-------------------------------------|-------------------------|
| I/O <sub>1</sub> - I/O <sub>8</sub> | Data inputs and outputs |
| V <sub>cc</sub>                     | Power supply            |
| GND                                 | Ground                  |
| NC                                  | Non-connection          |

## TRUTH TABLE

| $\overline{CE}_1$ | $CE_2$ | $\overline{WE}$ | $\overline{OE}$ | MODE           | I/O <sub>1</sub> - I/O <sub>8</sub> | SUPPLY CURRENT               | NOTE |
|-------------------|--------|-----------------|-----------------|----------------|-------------------------------------|------------------------------|------|
| H                 | X      | X               | X               | Deselect       | High-Z                              | Standby (I <sub>SB</sub> )   | 1    |
| X                 | L      | X               | X               | Deselect       | High-Z                              | Standby (I <sub>SB</sub> )   | 1    |
| L                 | H      | L               | X               | Write          | D <sub>IN</sub>                     | Operating (I <sub>CC</sub> ) |      |
| L                 | H      | H               | L               | Read           | D <sub>OUT</sub>                    | Operating (I <sub>CC</sub> ) |      |
| L                 | H      | H               | H               | Output disable | High-Z                              | Operating (I <sub>CC</sub> ) |      |

## NOTE:

1. X = H or L

## ABSOLUTE MAXIMUM RATINGS

| PARAMETER             | SYMBOL           | 80 ns                        | 100 ns                       | UNIT | NOTE |
|-----------------------|------------------|------------------------------|------------------------------|------|------|
|                       |                  | RATING                       | RATING                       |      |      |
| Supply voltage        | V <sub>CC</sub>  | -0.3 to +7.0                 | -0.3 to +7.0                 | V    | 1    |
| Input voltage         | V <sub>IN</sub>  | -0.5 to V <sub>CC</sub> +0.5 | -0.3 to V <sub>CC</sub> +0.3 | V    | 1    |
| Operating temperature | T <sub>opr</sub> | -10 to +70                   | -10 to +70                   | °C   | 2    |
|                       |                  |                              | -40 to +85                   | °C   | 3    |
| Storage temperature   | T <sub>stg</sub> | -55 to +150                  | -55 to +150                  | °C   |      |

## NOTES:

1. The maximum applicable voltage on any pin with respect to GND.
2. LH5168/D/N
3. LH5168H/HD/HN

## RECOMMENDED OPERATING CONDITIONS (Note 1)

| PARAMETER      | SYMBOL          | 80 ns |      |                       | 100 ns |      |                       | UNIT |
|----------------|-----------------|-------|------|-----------------------|--------|------|-----------------------|------|
|                |                 | MIN.  | TYP. | MAX.                  | MIN.   | TYP. | MAX.                  |      |
| Supply voltage | V <sub>CC</sub> | 4.5   | 5.0  | 5.5                   | 4.5    | 5.0  | 5.5                   | V    |
| Input voltage  | V <sub>IH</sub> | 2.2   |      | V <sub>CC</sub> + 0.5 | 2.2    |      | V <sub>CC</sub> + 0.3 | V    |
|                | V <sub>IL</sub> | -0.5  |      | 0.8                   | -0.3   |      | 0.8                   | V    |

## NOTE:

1. T<sub>A</sub> = -10 to +70°C (LH5168/D/N), T<sub>A</sub> = -40 to +85°C (LH5168H/HD/HN).

DC CHARACTERISTICS<sup>1</sup> (V<sub>CC</sub> = 5 V ± 10%)

| PARAMETER              | SYMBOL           | CONDITIONS  | MIN.   | MAX.       | UNIT | NOTE   |
|------------------------|------------------|---|--|------------|------|--------|
| Input leakage current  | I <sub>LI</sub>  | V <sub>IN</sub> = 0 to V <sub>CC</sub>  |  | 1.0        | μA   |        |
| Output leakage current | I <sub>LO</sub>  | $\overline{CE}_1 = V_{IH}$ or $CE_2 = V_{IL}$<br>or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$<br>V <sub>I/O</sub> = 0 to V <sub>CC</sub> |  | 1.0        | μA   |        |
| Operating current      | I <sub>CC</sub>  | $\overline{CE}_1 = V_{IL}$ , V <sub>IN</sub> = V <sub>IL</sub> to V <sub>IH</sub><br>CE <sub>2</sub> = V <sub>IH</sub> , Outputs open               | t <sub>CYCLE</sub> =<br>80 ns                  | 55         | mA   |        |
|                        |                  | $\overline{CE}_1 = V_{IL}$ , V <sub>IN</sub> = V <sub>IL</sub> to V <sub>IH</sub><br>CE <sub>2</sub> = V <sub>IH</sub> , Outputs open               | t <sub>CYCLE</sub> =<br>100 ns                 | 45<br>50   | mA   | 2<br>3 |
|                        |                  | $\overline{CE}_1 = V_{IL}$ , V <sub>IN</sub> = 0.2 V to<br>V <sub>CC</sub> - 0.2 V<br>CE <sub>2</sub> = V <sub>IH</sub> , Outputs open              | t <sub>CYCLE</sub> =<br>1.0 μs                 | 10         | mA   |        |
| Standby current        | I <sub>SB1</sub> | $\overline{CE}_1 = V_{IH}$ or $CE_2 = V_{IL}$   |  | 10         | mA   |        |
|                        | I <sub>SB</sub>  | CE <sub>2</sub> ≤ 0.2 V or<br>$\overline{CE}_1$ , CE <sub>2</sub> ≥ V <sub>CC</sub> - 0.2 V   | T <sub>A</sub> ≤ 70°C<br>T <sub>A</sub> ≤ 85°C | 1.0<br>3.0 | μA   | 2<br>3 |
| Output voltage         | V <sub>OL</sub>  | I <sub>OL</sub> = 2.1 mA  |  | 0.4        | V    |        |
|                        | V <sub>OH</sub>  | I <sub>OH</sub> = -1 mA   | 2.4  |            | V    |        |

## NOTES:

1. T<sub>A</sub> = -10 to 70°C (LH5168/D/N/T/TR), T<sub>A</sub> = -40 to +85°C (LH5168H/HD/HN)
2. LH5168/D/N/T/TR
3. LH5168H/HD/HN

AC CHARACTERISTICS<sup>1</sup>(1) READ CYCLE ( $V_{CC} = 5 V \pm 10\%$ )

| PARAMETER                          | SYMBOL                         | 80 ns |      | 100 ns |      | UNIT | NOTE |
|------------------------------------|--------------------------------|-------|------|--------|------|------|------|
|                                    |                                | MIN.  | MAX. | MIN.   | MAX. |      |      |
| Read cycle                         | $t_{RC}$                       | 80    |      | 100    |      | ns   |      |
| Address access time                | $t_{AA}$                       |       | 80   |        | 100  | ns   |      |
| Chip enable access time            | $(\overline{CE}_1)$ $t_{ACE1}$ |       | 80   |        | 100  | ns   |      |
|                                    | $(CE_2)$ $t_{ACE2}$            |       | 80   |        | 100  | ns   |      |
| Output enable access time          | $t_{OE}$                       |       | 40   |        | 40   | ns   |      |
| Output hold time                   | $t_{OH}$                       | 10    |      | 10     |      | ns   |      |
| Chip enable to output in Low-Z     | $(\overline{CE}_1)$ $t_{LZ1}$  | 10    |      | 10     |      | ns   | 2    |
|                                    | $(CE_2)$ $t_{LZ2}$             | 10    |      | 10     |      | ns   | 2    |
| Output enable to output in Low-Z   | $t_{OLZ}$                      | 5     |      | 5      |      | ns   | 2    |
| Chip enable to output in High-Z    | $(\overline{CE}_1)$ $t_{HZ1}$  | 0     | 30   | 0      | 30   | ns   | 2    |
|                                    | $(CE_2)$ $t_{HZ2}$             | 0     | 30   | 0      | 30   | ns   | 2    |
| Output disable to output in High-Z | $t_{OHZ}$                      | 0     | 20   | 0      | 20   | ns   | 2    |

## NOTES:

- $T_A = -10$  to  $+70^\circ\text{C}$  (LH5168/D/N/T/TR),  $T_A = -40$  to  $+85^\circ\text{C}$  (LH5168H/HD/HN)
- Active output to high-impedance and high-impedance to output active tests specified for a  $\pm 500$  mV transition from steady state levels into the test load.  $C_{LOAD} = 5$  pF.

(2) WRITE CYCLE ( $V_{CC} = 5 V \pm 10\%$ )

| PARAMETER                           | SYMBOL    | 80 ns |      | 100 ns |      | UNIT | NOTE |
|-------------------------------------|-----------|-------|------|--------|------|------|------|
|                                     |           | MIN.  | MAX. | MIN.   | MAX. |      |      |
| Write cycle time                    | $t_{WC}$  | 80    |      | 100    |      | ns   |      |
| Chip enable to end of write         | $t_{CW}$  | 70    |      | 80     |      | ns   |      |
| Address valid to end of write       | $t_{AW}$  | 70    |      | 80     |      | ns   |      |
| Address setup time                  | $t_{AS}$  | 0     |      | 0      |      | ns   |      |
| Write pulse width                   | $t_{WP}$  | 60    |      | 60     |      | ns   |      |
| Write recovery time                 | $t_{WR}$  | 0     |      | 0      |      | ns   |      |
| Data valid to end of write          | $t_{DW}$  | 40    |      | 40     |      | ns   |      |
| Data hold time                      | $t_{DH}$  | 0     |      | 0      |      | ns   |      |
| Output active from end of write     | $t_{OW}$  | 10    |      | 10     |      | ns   | 1    |
| $\overline{WE}$ to output in High-Z | $t_{WZ}$  | 0     | 30   | 0      | 30   | ns   | 1    |
| $\overline{OE}$ to output in High-Z | $t_{OHZ}$ | 0     | 20   | 0      | 20   | ns   | 1    |

## NOTE:

- Active output to high-impedance and high-impedance to output active tests specified for a  $\pm 500$  mV transition from steady state levels into the test load.  $C_{LOAD} = 5$  pF.

## AC TEST CONDITIONS

| PARAMETER               | MODE                    |
|-------------------------|-------------------------|
| Input voltage amplitude | 0.6 to 2.4 V            |
| Input rise/fall time    | 10 ns                   |
| Timing reference level  | 1.5 V                   |
| Output load conditions  | (1TTL + $C_L = 100$ pF) |

SHARP CORP

6LE D ■ 8180798 0009706 320 ■ SRPJ

CAPACITANCE <sup>1</sup> (T<sub>A</sub> = 25°C, f = 1MHz)

| PARAMETER                | SYMBOL          | CONDITIONS            | MIN. | TYP. | MAX. | UNIT |
|--------------------------|-----------------|-----------------------|------|------|------|------|
| Input capacitance        | C <sub>IN</sub> | V <sub>IN</sub> = 0 V |      |      | 7    | pF   |
| Input/output capacitance | C <sub>IO</sub> | V <sub>IO</sub> = 0 V |      |      | 10   | pF   |

NOTE:

1. This parameter is sampled and not production tested.

DATA RETENTION CHARACTERISTICS <sup>1</sup>

| PARAMETER                      | SYMBOL            | CONDITIONS  | MIN.            | MAX. | UNIT | NOTE |
|--------------------------------|-------------------|---|-----------------|------|------|------|
| Data retention voltage         | V <sub>CCDR</sub> | CE <sub>2</sub> ≤ 0.2 V or<br>CE <sub>1</sub> , CE <sub>2</sub> ≥ V <sub>CC</sub> - 0.2 V                               | 2.0             |      | V    |      |
| Data retention current         | I <sub>CCDR</sub> | V <sub>CCDR</sub> = 3 V,<br>CE <sub>2</sub> ≤ 0.2 V or CE <sub>1</sub> ,<br>CE <sub>2</sub> ≥ V <sub>CCDR</sub> - 0.2 V |                 | 0.6  | μA   | 2    |
|                                |                   |   |                 | 1.5  | μA   | 3    |
| Chip disable to data retention | t <sub>CDR</sub>  |   | 0               |      | ns   |      |
| Recovery time                  | t <sub>RDR</sub>  |   | t <sub>RC</sub> |      | ns   | 4    |

NOTES:

1. T<sub>A</sub> = -10 to +70°C (LH5168/D/N/T/TR), T<sub>A</sub> = -40 to +85°C (LH5168H/HD/HN)
2. LH5168/D/N/T/TR at T<sub>A</sub> ≤ 70°C
3. LH5168H/HD/HN at T<sub>A</sub> ≤ 85°C
4. t<sub>RC</sub> = Read cycle time

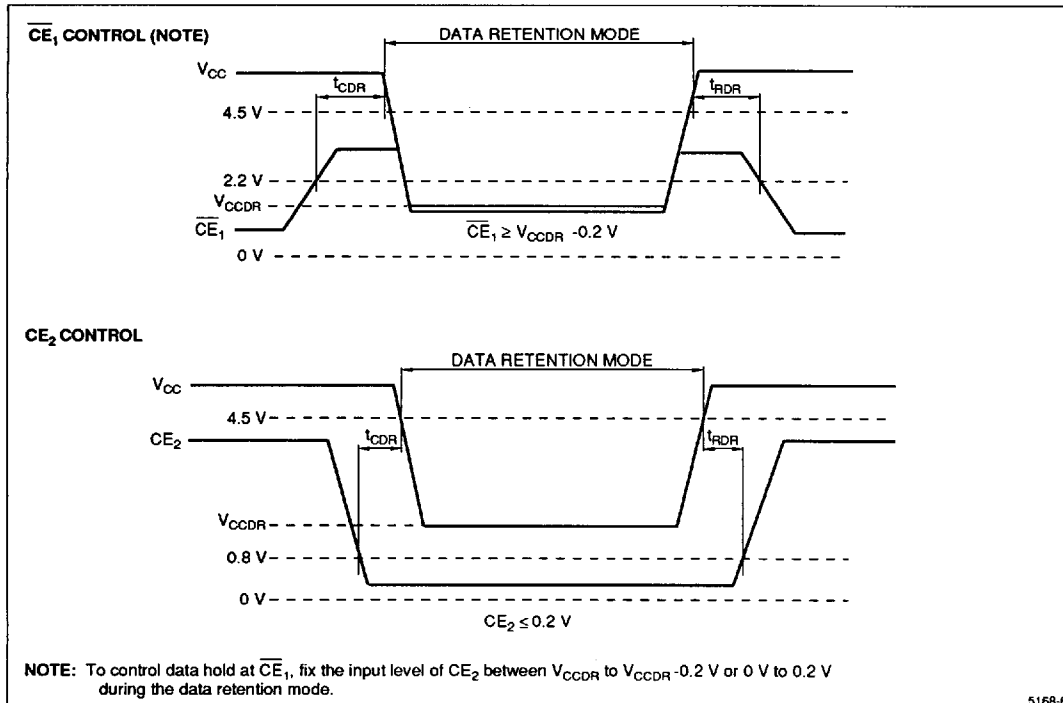
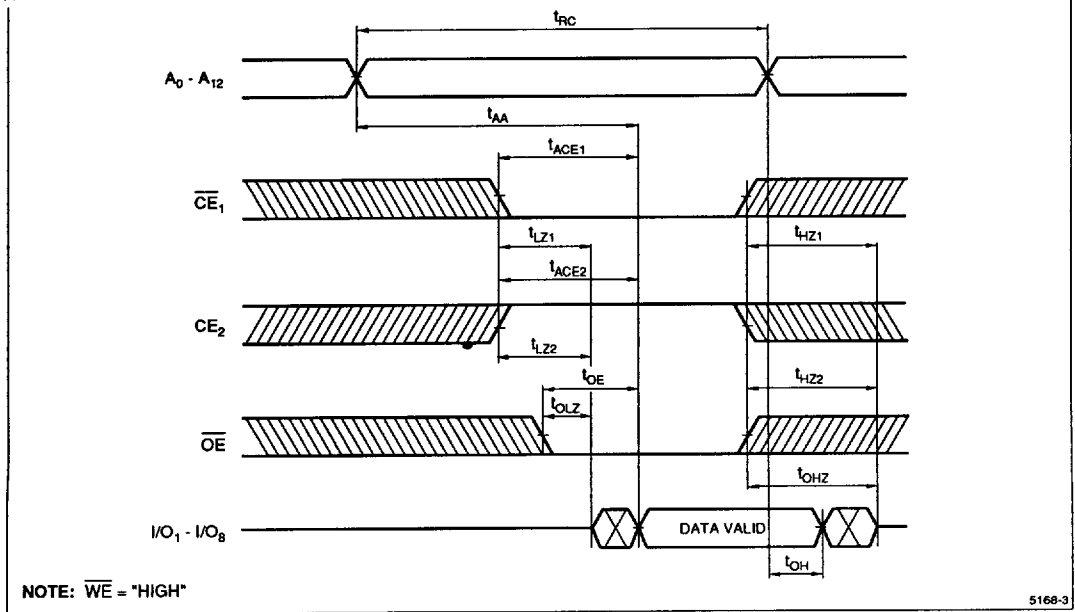


Figure 4. Low Voltage Data Retention

SHARP CORP

61E D ■ 8180798 0009707 267 ■ SRPJ

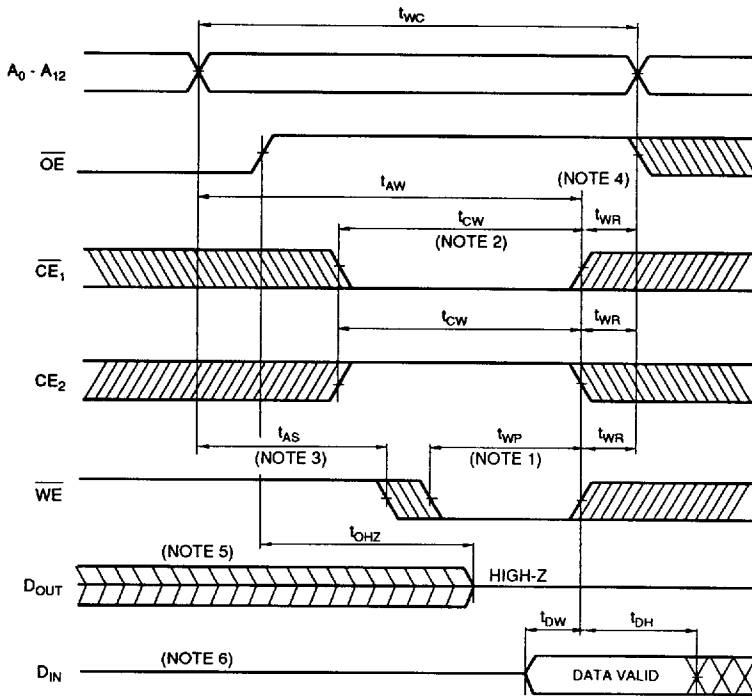


5168-3

Figure 5. Read Cycle

SHARP CORP

6LE D ■ 8180798 0009708 1T3 ■ SRPJ



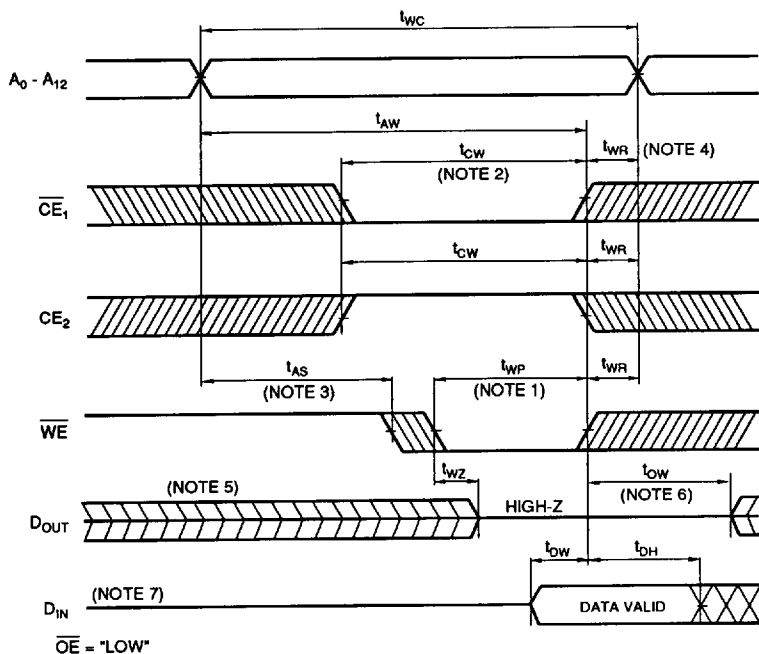
NOTES:

1. The writing occurs during the overlap ( $t_{WP}$ ) of  $\overline{CE}_1$  = "LOW",  $CE_2$  = "HIGH", and  $\overline{WE}$  = "LOW".
2.  $t_{CW}$  is defined as the time from the last occurring transition, either  $\overline{CE}_1$  LOW transition or  $CE_2$  HIGH transition, to the time when the writing is finished.
3.  $t_{AS}$  is defined as the time from address change to writing start.
4.  $t_{WR}$  is defined as the time from writing finish to address change.
5. If  $\overline{CE}_1$  LOW transition or  $CE_2$  HIGH transition occurs at the same time or after  $\overline{WE}$  LOW transition, the output will remain high-impedance.
6. While the I/O pins are in the output state, input signals with the opposite logic level must not be applied.

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Figure 6. Write Cycle 1





**NOTES:**

1. The writing occurs during the overlap (t<sub>WP</sub>) of  $\overline{CE}_1 = \text{"LOW"}$ , CE<sub>2</sub> = "HIGH", and  $\overline{WE} = \text{"LOW"}$ .
2. t<sub>CW</sub> is defined as the time from the last occurring transition, either  $\overline{CE}_1$  LOW transition or CE<sub>2</sub> HIGH transition, to the time when the writing is finished.
3. t<sub>AS</sub> is defined as the time from address change to writing start.
4. t<sub>WR</sub> is defined as the time from writing finish to address change.
5. If  $\overline{CE}_1$  LOW transition or CE<sub>2</sub> HIGH transition occurs at the same time or after  $\overline{WE}$  LOW transition, the output will remain high-impedance.
6. If  $\overline{CE}_1$  HIGH transition or CE<sub>2</sub> LOW transition occurs at the same time or before  $\overline{WE}$  HIGH transition, the output will remain high-impedance.
7. While the I/O pins are in the output state, input signals with the opposite logic level must not be applied.

5168-5

Figure 7. Write Cycle 2

**ORDERING INFORMATION**

| LH5168   | X                     | X       | - ##  |  |
|--|-----------------------|---------|-------|--|
| Device Type  | Operating Temperature | Package | Speed |  |
|  |                       |         |       | { 10L 100 Access Time (ns)   |
|  |                       |         |       | { 80L 80   |
|  |                       |         |       | { Blank 28 pin, 600-mil DIP (DIP 28-P-600)                                     |
|  |                       |         |       | { D 28-pin, 300-mil SK-DIP (SK-DIP28-P-300)                                    |
|  |                       |         |       | { N 28-pin, 450-mil SOP (SOP28-P-450)  |
|  |                       |         |       | { T 28-pin, 8 x 13 mm <sup>2</sup> TSOP (Type I) (TSOP28-P-0813)               |
|  |                       |         |       | { TR 28-pin, 8 x 13 mm <sup>2</sup> TSOP (Type I) Reverse Bend (TSOP28-P-0813) |
|  |                       |         |       | { Blank -10 to 70°C  |
|  |                       |         |       | { H -40 to +85°C   |
| CMOS 64K (8K x 8) Static RAM   |                       |         |       |  |
| <b>Example:</b> LH5168D-10L (CMOS 64K (8K x 8) Static RAM, 100 ns, 28-pin, 300-mil SK-DIP) |                       |         |       |  |

5168-7